



100V N-Channel Enhancement Mode MOSFET

Voltage

100 V

Current

42 A

Features

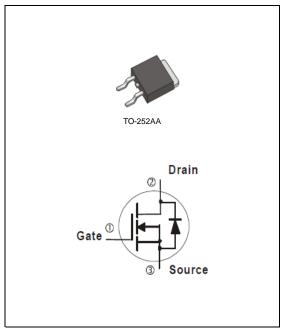
- RDS(ON), VGS@10V, ID@20A<25mΩ
- RDS(ON) , VGS@4.5V, ID@15A<28.5m Ω
- Advanced Trench Process Technology
- High density cell design for ultra low on-resistance
- Lead free in compliance with EU RoHS 2011/65/EU directive
- Green molding compound as per IEC61249 Std.. (Halogen Free)



• Case: TO-252AA Package

• Terminals : Solderable per MIL-STD-750, Method 2026

• Approx. Weight: 0.0104 ounces, 0.297grams



Maximum Ratings and Thermal Characteristics (T_A=25 °C unless otherwise noted)

PARAMETER		SYMBOL	LIMIT	UNITS	
Drain-Source Voltage		V _{DS}	100	V	
Gate-Source Voltage		V_{GS}	<u>+</u> 20	V	
Continuous Drain Current	T _C =25°C	l _D	42	A	
	T _C =100°C		26		
Pulsed Drain Current (Note 1)	T _C =25°C	I _{DM}	150		
Power Dissipation	T _C =25°C	Po	83	W	
	T _C =100°C		33		
Continuous Drain Current	T _A =25°C	I _D	6.3	Α	
	T _A =70°C		5.1	Α	
Power Dissipation	T _A =25°C	D-	2.0	W	
Power Dissipation	T _A =70°C	Pb	1.3		
Single Pulse Avalanche Energy (Note 6)		E _{AS}	63.4	mJ	
Operating Junction and Storage Temperature Range		T_{J} , T_{STG}	-55~150	°C	
Typical Thermal Resistance (Note 4,5)	Junction to Case	$R_{ heta JC}$	1.5	°C/W	
	Junction to Ambient	$R_{\theta JA}$	62.5		

Limited only By Maximum Junction Temperature





Electrical Characteristics (T_A=25°C unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNITS
Static						
Drain-Source Breakdown Voltage	BV _{DSS}	V_{GS} =0V, I_D =250uA	100	-	-	V
Gate Threshold Voltage	$V_{GS(th)}$	V _{DS} =V _{GS} , I _D =250uA	1.0	1.8	2.5	V
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} =10V,I _D =20A	-	20	25	mΩ
		V _{GS} =4.5V,I _D =15A	-	22	28.5	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =80V,V _{GS} =0V	-	-	1.0	uA
Gate-Source Leakage Current	I_{GSS}	V _{GS} = <u>+</u> 20V,V _{DS} =0V	-	-	<u>+</u> 100	nA
Dynamic (Note 7)						
Total Gate Charge	Q_g	V _{DS} =50V, I _D =10A, V _{GS} =10V ^(Note 1,2)	-	29	-	nC
Gate-Source Charge	Q_gs		-	4.5	-	
Gate-Drain Charge	Q_gd	V _{GS} =10V	-	6.4	-	
Input Capacitance	Ciss	V _{DS} =30V, V _{GS} =0V,	-	1485	-	pF
Output Capacitance	Coss		-	135	-	
Reverse Transfer Capacitance	Crss	I=1.0IVII IZ	-	67	-	
Turn-On Delay Time	td _(on)	\/ F0\/ 10A	-	7.8	-	
Turn-On Rise Time	t _r	V _{DD} =50V, I _D =10A,	-	30	-	ns
Turn-Off Delay Time	td _(off)	$V_{GS}=10V$, $R_{G}=3\Omega$ (Note 1,2)	-	35	-	
Turn-Off Fall Time	t _f	NG=312	-	14	-	
Drain-Source Diode						
Maximum Continuous Drain-Source	I.				42	Α
Diode Forward Current	I _S		-	_	42	Α
Diode Forward Voltage	V_{SD}	I _S =1.0A, V _{GS} =0V	_	0.7	1.2	V

NOTES:

- 1. Pulse width<a>300us, Duty cycle<a>2%
- 2. Essentially independent of operating temperature typical characteristics.
- 3. Repetitive rating, pulse width limited by junction temperature TJ(MAX)=150°C. Ratings are based on low frequency and duty cycles to keep initial TJ=25°C.
- 4. The maximum current rating is package limited.
- 5. R_{OJA} is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. Mounted on a 1 inch² with 2oz.square pad of copper.
- 6. The test condition is L=3mH, I_{AS} =6.5A, V_{DD} =25V, V_{GS} =10V
- 7. Guaranteed by design, not subject to production testing.





TYPICAL CHARACTERISTIC CURVES

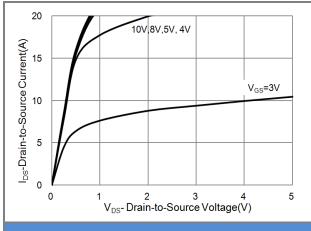


Fig.1 Output Characteristics

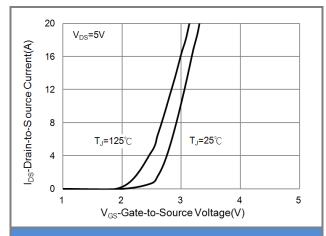


Fig.2 Transfer Characteristics

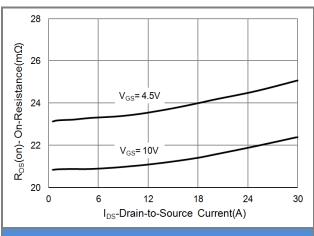


Fig.3 On-Resistance vs. Drain Current

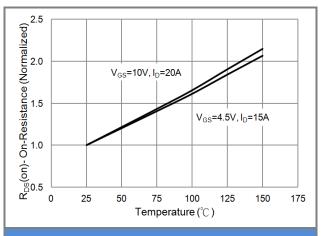


Fig.4 On-Resistance vs. Junction temperature

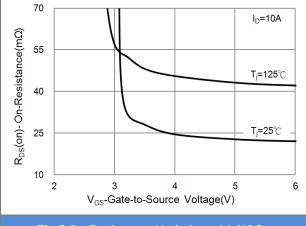


Fig.5 On-Resistance Variation with VGS.

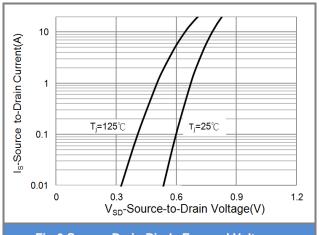


Fig.6 Source-Drain Diode Forward Voltage





TYPICAL CHARACTERISTIC CURVES

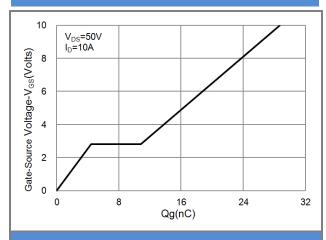
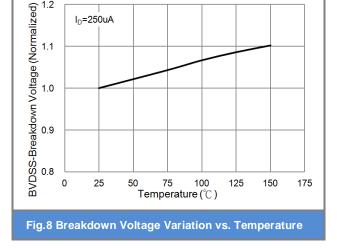


Fig.7 Gate-Charge Characteristics



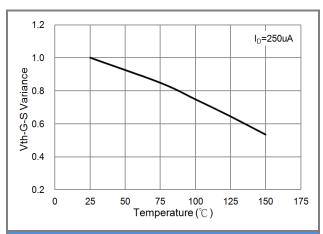


Fig.9 Threshold Voltage Variation with Temperature

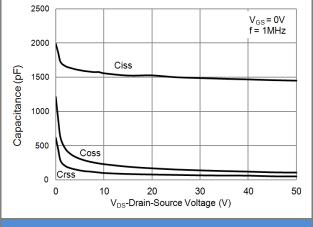


Fig.10 Capacitance vs. Drain-Source Voltage

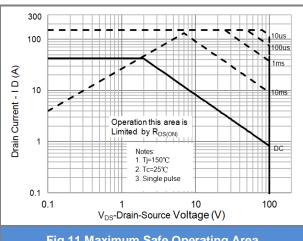


Fig.11 Maximum Safe Operating Area





TYPICAL CHARACTERISTIC CURVES

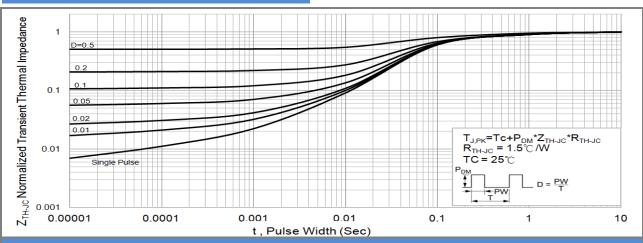
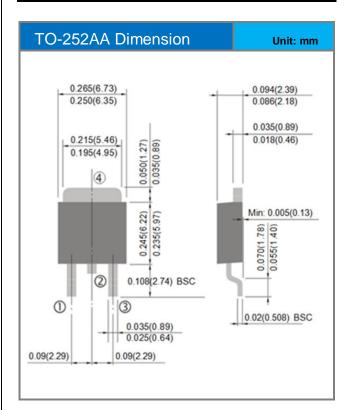


Fig.12 Normalized Transient Thermal Impedance vs. Pulse Width





Packaging Information



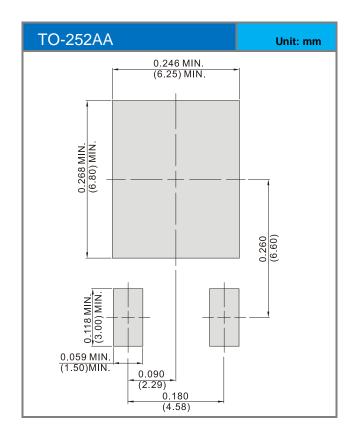




PART NO PACKING CODE VERSION

Part No Packing Code	Package Type	Packing Type	Marking	Version	
PJD50N10AL_L2_00001	TO-252AA	3,000pcs / 13" reel	50N10AL	Halogen free	

MOUNTING PAD LAYOUT







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